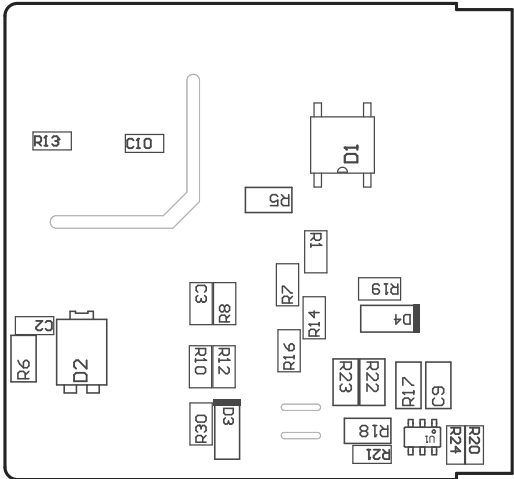


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP40228	REV: A	SVN REV: Not In VersionControl
	TID #: PMP40228		
PLOT NAME = Top Assembly Drawing	GENERATED : 4/7/2017 2:16:11 PM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP40228	REV: A	SVN REV: Not In VersionControl
	TID #: PMP40228		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 4/7/2017 2:16:12 PM		TEXAS INSTRUMENTS

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